

L Number	Hits	Search Text	DB	Time stamp
1	2	((("5399041") or ("5220195"))).PN.	USPAT	2003/01/27 04:52
2	2	((("5399904") or ("5220195"))).PN.	USPAT	2003/01/27 05:47
3	68	257/737.ccls. and (solder adj mask)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 05:50
4	77	257/737.ccls. and cap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 07:00
5	98	257/737.ccls. and ((low and high) with solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 06:05
6	2276	solder with cap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 06:08
7	71	(solder with cap) and ((low and high) near melt\$3)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 06:28
8	1	6229220.URPN.	USPAT	2003/01/27 06:17
9	30	5796591.URPN.	USPAT	2003/01/27 06:21
10	1	("5796591").PN.	USPAT	2003/01/27 06:30
11	13042	cap and mask	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 06:30
12	0	((au near cap) same solder) and mask	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 06:31
13	364	(cap same solder) and mask	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 06:49
14	2	(au near cap) same solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 06:51
15	223	(cylinder or cylindrical) near solder	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 07:03
16	88	257/738.ccls. and cap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 07:01
17	2697	(cylinder or cylindrical) near (ball or bump or solder)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 07:04
18	366	((cylinder or cylindrical) near (ball or bump or solder)) and cap	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/01/27 07:05

19	32	((cylinder or cylindrical) near (ball or bump or solder)) and cap) and (semiconductor or chip or die)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/01/27 07:05
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